

Power Bridge Rectifiers

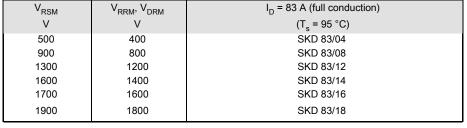
SKD 83

Features

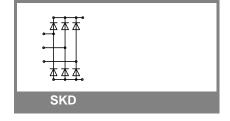
- · Glass passivated silicon chips
- Low thermal impedance through use of direct copper bonded aluminum substrate (DCB) base plate
- Blocking voltage up to 1800 V
- Suitable for PCB mounting and wave soldering
- For applications with high vibrations we recommend to fasten the bridge to the pcb with 4 selftapping screw

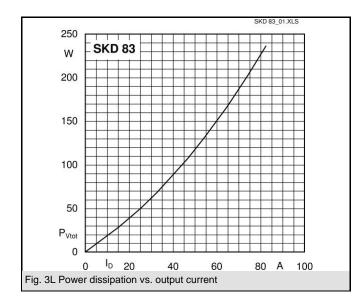
Typical Applications

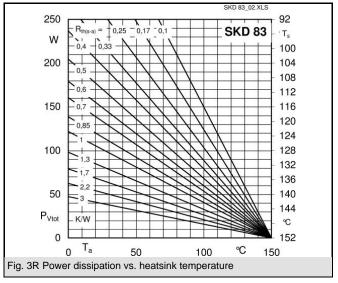
- Three phase rectifiers for power supplies
- Input rectifiers for variable frequency drives
- Rectifiers for DC motor field supplies
- · Battery charger rectifiers
- Freely suspended or mounted on an insulator
- 2) Mounted on a painted metal sheet of min. 250 x 250 x 1 mm
- 3) $T_{solder} = 250 \pm 10 \, ^{\circ}C \, (10 \, s)$

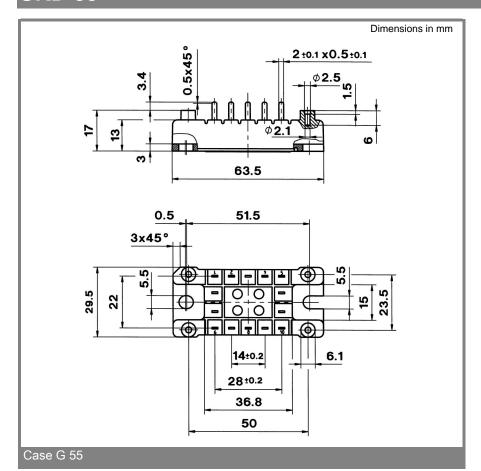


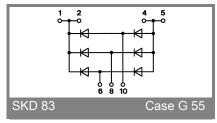
Symbol	Conditions	Values	Units
I _D	T _s = 95 °C	83	Α
	T _a = 45 °C; isolated ¹⁾	4	Α
	$T_a = 45 ^{\circ}\text{C}$; chassis ²⁾	20	Α
	$T_a = 45 ^{\circ}\text{C}; P5A/100 (R4A/120)$	32 (34)	Α
	T _a = 35 °C; P1A/120F	83	Α
I _{FSM}	T _{vj} = 25 °C; 10 ms	700	Α
	T _{vj} = 150 °C; 10 ms	560	Α
i²t	T _{vj} = 25 °C; 8,3 10 ms	2450	A²s
	T _{vj} = 150 °C; 8,3 10 ms	1570	A²s
V _F	T _{vi} = 25 °C; I _F = 80 A	max. 1,45	V
$V_{(TO)}$	T _{vi} = 150 °C	max. 0,8	V
r _T	T _{vi} = 150 °C	max. 7,5	mΩ
I_{RD}	$T_{vi} = 25 ^{\circ}C; V_{DD} = V_{DRM}; V_{RD} = V_{RRM}$	max. 0,2	mA
	$T_{vj} = 150 ^{\circ}\text{C}; V_{RD} = V_{RRM}$	4	mA
$R_{th(j-s)}$	per diode	1,4	K/W
	total	0,233	K/W
$R_{th(j-a)}$	isolated 1)	14,83	K/W
	chassis ²⁾	2,83	K/W
$T_{v_{j}}$		- 40 + 150	°C
T _{stg}		- 40 + 125 ³⁾	°C
V _{isol}	a. c. 50 Hz; r.m.s.; 1 s / 1 min.	3600 (3000)	V
M _s	to heatsink; SI units	2 ± 15 %	Nm
M _t			
а		5 * 9,81	m/s²
m		30	g
Case		G 55	











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